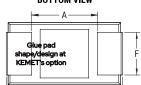


## T545W477M006ATE035

T545, Tantalum, Polymer Tantalum, Commercial Grade, 470 uF, 20%, 6.3 VDC, SMD, Polymer, Molded, Low Profile, HiEnergyDensity, 35 mOhms, 7343, 1.5 mm, 1.3 mm

CATHODE (-) END VIEW SIDE VIEW Termination cutout at KEMET's option, either end ANODE (+) END VIEW Glup part



Click here for the 3D model.

Dimensions	
L	7.3mm +/-0.3mm
W	4.3mm +/-0.3mm
н	1.4mm +/-0.1mm
т	0.13mm REF
S	1.3mm +/-0.3mm
F	2.4mm +/-0.1mm
A	3.8mm MIN
Х	0.05mm REF

# Packaging Specifications

Packaging	T&R, 178mm
Packaging Quantity	1000

General Information	
Series	T545
Dielectric	Polymer Tantalum
Style	SMD Chip
Description	SMD, Polymer, Molded, Low Profile, HiEnergyDensity
Features	Low ESR
RoHS	Yes
Termination	Tin
AEC-Q200	No
Typical Component Weight	222.94 mg
Shelf Life	52 Weeks
MSL	3

Specifications	
Capacitance	470 uF
Tolerance	20%
Voltage DC	6.3 VDC (105C)
Temperature Range	-55/+105°C
Rated Temperature	105°C
Humidity	60C, 90% RH, 500 Hours, No Load
Dissipation Factor	10% 120Hz 25C
Failure Rate	N/A
ESR	35 mOhms (100kHz 25C)
Ripple Current	2270 mA (rms, 100kHz 45C), 1589 mA (rms, 85C), 567.5 mA (rms, 105C)
Leakage Current	296.1 uA (5min 25°C)

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.



### T545W477M006ATE035

10.0 m

6.3 m

4.0 m

2.5 m

1.6 m

1.0 m

0.6 m

0.4 m

Capacitance (F)

40.0

20.0

0.0

-20.0

-40.0

-60.0

-80.0

Phase

°

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Capacitance and Inductance

10.0 n

3.2 n

1.0 n

0.3 n

100.0 p

31.6 p

10.0 p

150.0

100.0

50.0

0.0

-50.0

-100.0

-150.0

10.0 G

Phase (°)

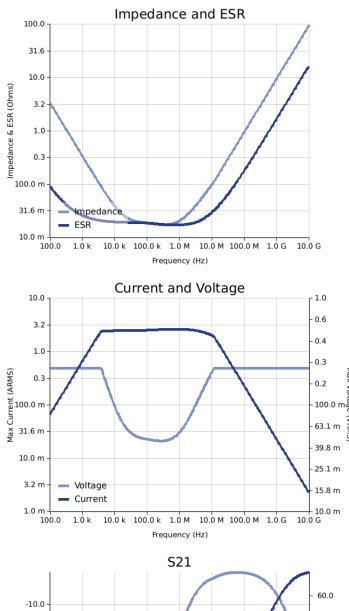
10.0 G

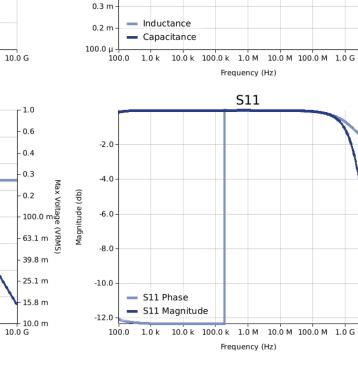
Inductan

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### Simulations

For the complete simulation environment please visit K-SIM.





-20.0

-30.0

-40.0

Generated 05/14/2025

Magnitude (db)



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#### These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics.
  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.